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## IEEE Symposium on Low-Power and High-Speed Chips

# COOL Chips XVI

Yokohama Joho Bunka Center, Yokohama, Japan  
(Yokohama Media & Communications Center, Yokohama, Japan)

April 17 - 19, 2013

## CALL FOR CONTRIBUTIONS

COOL Chips is an International Symposium initiated in 1998 to present advancement of low-power and high-speed chips. The symposium covers leading-edge technologies in all areas of microprocessors and their applications. The COOL Chips XVI is to be held in Yokohama on April 17-19, 2013, and is targeted at the architecture, design and implementation of chips with special emphasis on the areas listed below. All papers will be published online via IEEE Xplore. Authors of best papers will be recommended to submit an extended version to a COOL Chips special issue of IEEE Micro.

### Contributions are solicited in the following areas:

- **Low Power-High Performance Processors for -  
Multimedia, Digital Consumer Electronics, Mobile, Graphics, Encryption, Robotics,  
Automotive, Networking, Medical, Healthcare, and Biometrics.**
- **Novel Architectures and Schemes for -  
Single Core, Multi/Many-Core, Embedded Systems, Reconfigurable Computing, Grid,  
Ubiquitous, Dependable Computing, GALS and Wireless.**
- **Cool Software including - Parallel Schedulers, Embedded Real-time Operating System,  
Binary Translations, Compiler Issues and Low Power Techniques.**

Proposals should consist of a title, an extended abstract (up to 3 pages) describing the product or topic to be presented and the name, job title, address, phone number, FAX number, and e-mail address of the presenter. The status of the product or topic should precisely be described. If this is a not-yet-announced product, and you would like to keep the submission confidential, please indicate it. We will do our best to maintain confidentiality. Proposals will be selected by the program committee's evaluation of interest to the audience. Submission should be made by e-mail, (Author's kit can be obtained from <http://www.coolchips.org/>)

to: M. Ikeda, Program Chair e-mail: [submit\\_xvi@coolchips.org](mailto:submit_xvi@coolchips.org)

**Author Schedule: February 5, 2013 Extended Abstract Submission (by e-mail)**

**March 11, 2013 Acceptance Notified (by e-mail)**

**March 26, 2013 Final Manuscript Submission**

You are also invited to submit proposals for poster sessions by e-mail,

to: K. Hashimoto, Poster Chair e-mail: [poster\\_xvi@coolchips.org](mailto:poster_xvi@coolchips.org)

**Author Schedule: March 18, 2013 Poster Abstract Submission (by e-mail)**

**March 26, 2013 Poster Acceptance Notified (by e-mail)**

For more information, please visit <<http://www.coolchips.org/>>.

For any questions, please contact the Secretariat <[cool\\_xvi@coolchips.org](mailto:cool_xvi@coolchips.org)>.

Sponsored by the Technical Committees on Microprocessors and Microcomputers and Computer Architecture of the IEEE Computer Society. In cooperation with the IEICE Electronics Society and IPSJ.



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(As of November 29, 2012)